

ABSTRACT OF THE DISCLOSURE

A printed wiring board is provided in which lift-off and land peeling do not occur during soldering of an inserted component onto the printed wiring board, and hence pattern breakage does not occur, but with no increase in cost. A plurality of lands 6 are each formed continuously across surfaces of a substrate and an inner peripheral surface of one of a plurality of soldering through holes 5 into which leads 2 of an inserted component 3 to be mounted onto the printed wiring board are inserted before soldering is carried out, and a solder resist 8 is coated onto the lands 6.

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